

•

•

•

•

•

•

•

•

•

•

•

•

•

•

•

•

•

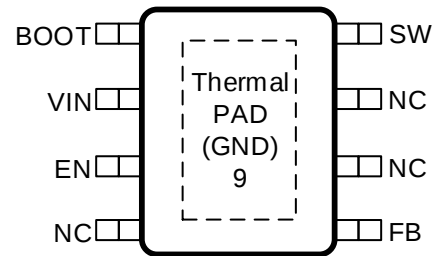
•

•

ORDERABLE DEVICE	PACKAGING TYPE	STANDARD PACK QTY	PACKAGE MARKING	PINS	PACKAGE DESCRIPTION

Over operating free-air temperature unless otherwise noted⁽¹⁾

DESCRIPTION	MIN	MAX	UNIT
BST	-0.3	40	V
VIN, SW, EN	-0.3	34	V
BST-SW	-0.3	6	V
FB	-0.3	5.5	V
Operating junction temperature ⁽²⁾	-40	125	C
Storage temperature T _{STG}	-65	150	C



8-Lead Plastic E-SOP

(1)

(2)

NAME	NO.	PIN FUNCTION
------	-----	--------------

PARAMETER	DEFINITION	MIN	MAX	UNIT

PARAMETER	DEFINITION	MIN	MAX	UNIT

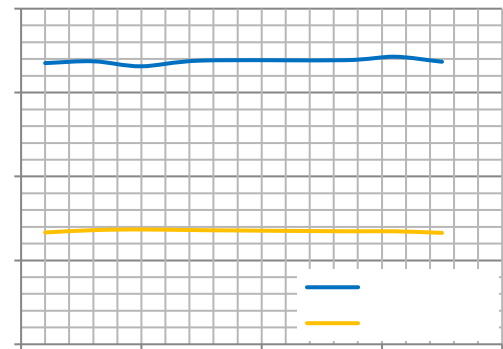
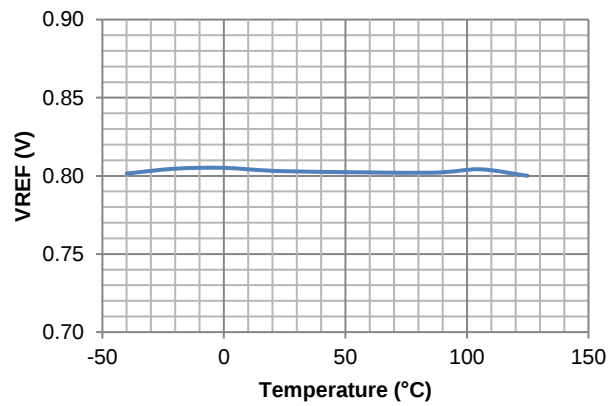
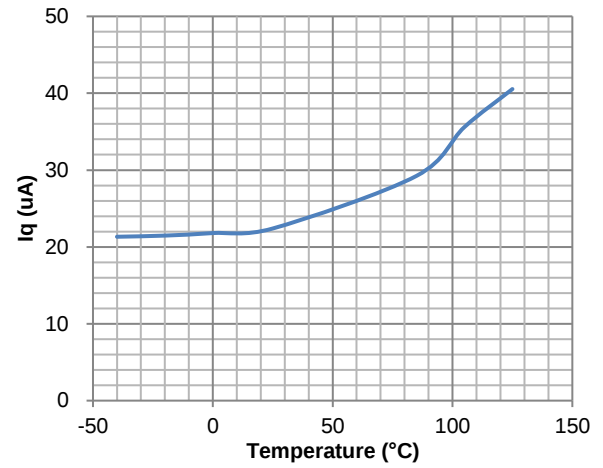
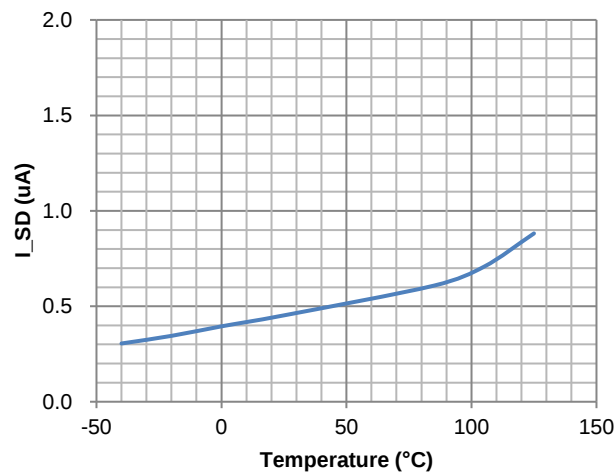
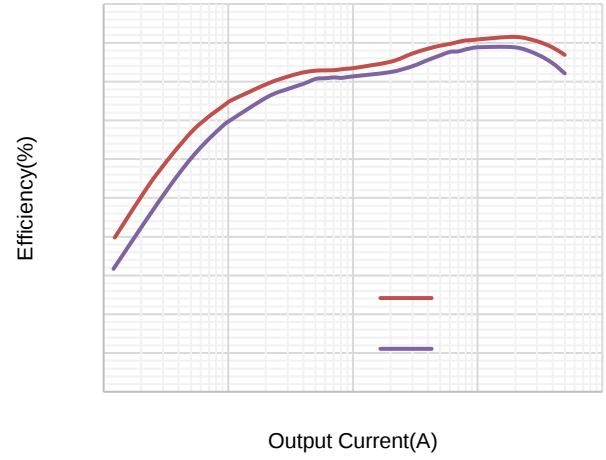
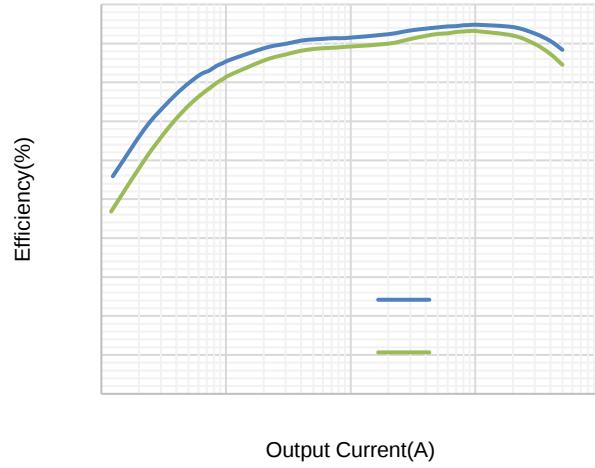
(1)
(2)

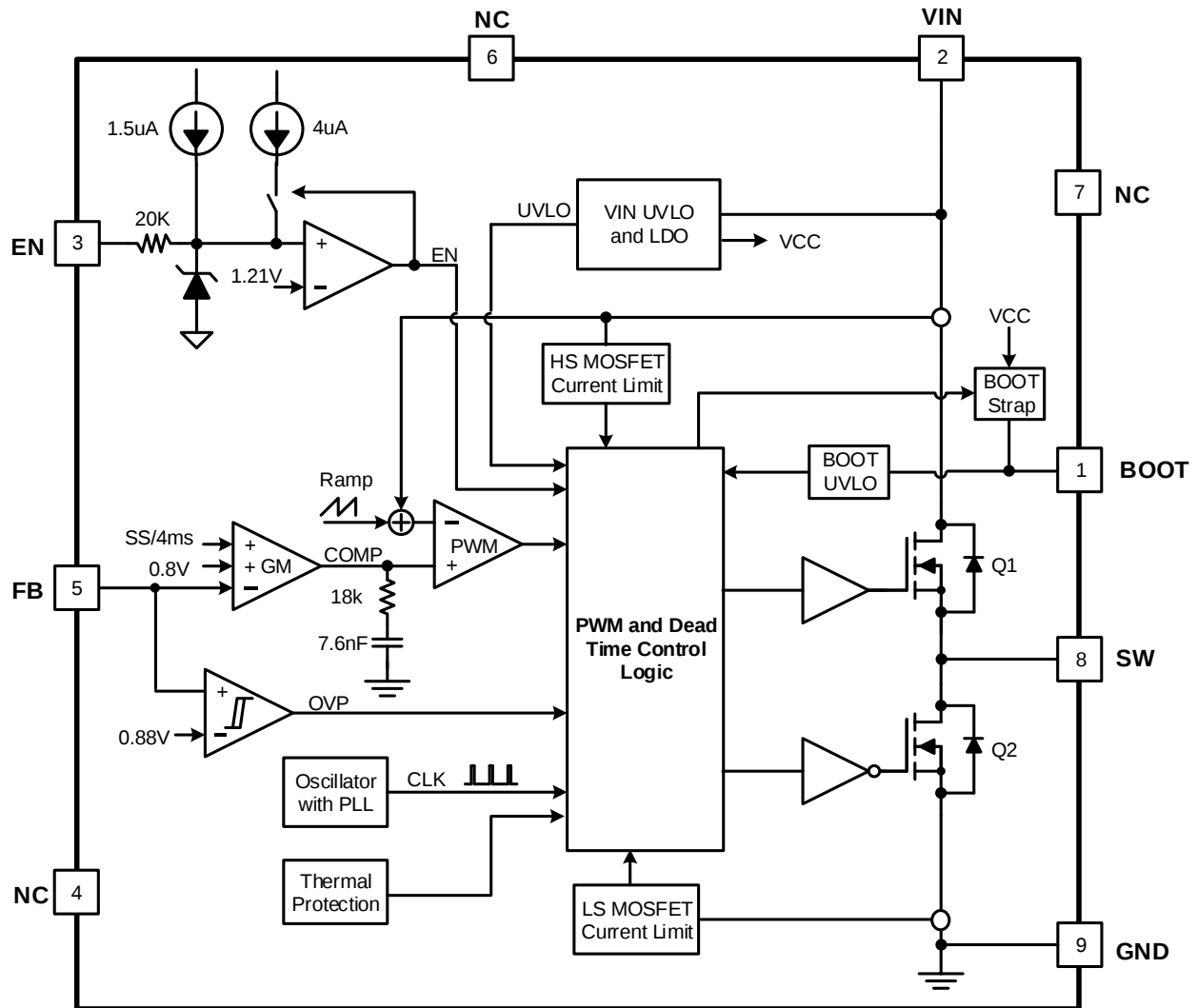
PARAMETER

THERMAL METRIC

ESOP

SYMBOL	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
Power Supply and Output						
Enable, Soft Start and Working Modes						
Power MOSFETs						
Feedback and Error Amplifier						
Current Limit						
Switching Frequency						
Soft Start Time						
Protection						



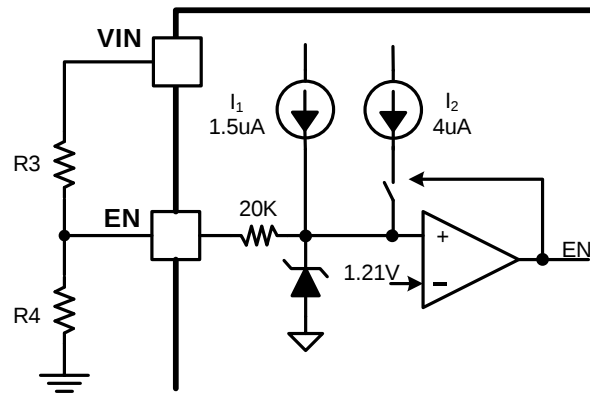


Overview

VIN Power

Under Voltage Lockout UVLO

Enable and Start up

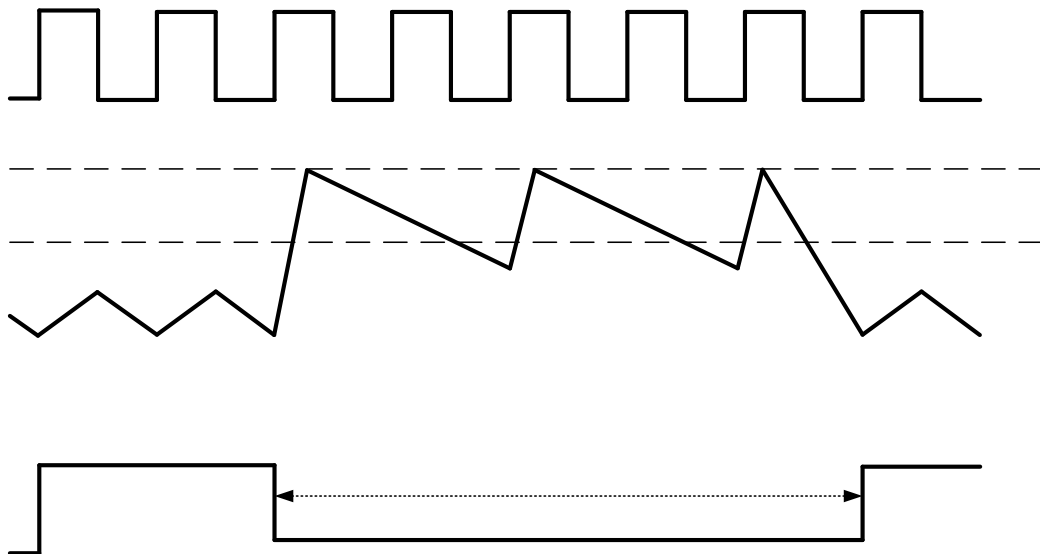


(1)

(2)

EMI Reduction with Frequency Spread Spectrum and Switching Node Ringing-free

Over Current Protection



Over Voltage Protection and Minimum On-time

PSM Working Modes

Bootstrap Voltage Regulator

Thermal Shutdown

°
°

Input Capacitor Selection

(3)

1 _____

-
-
-

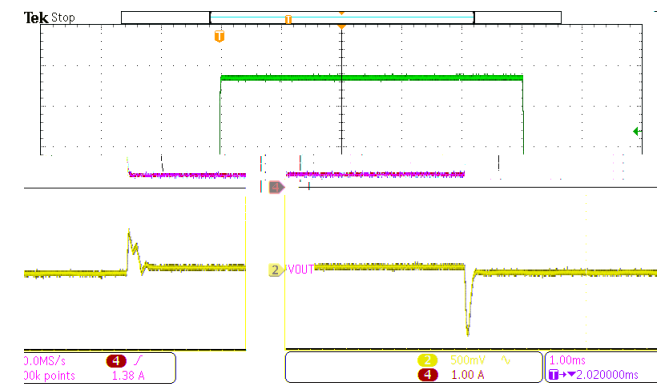
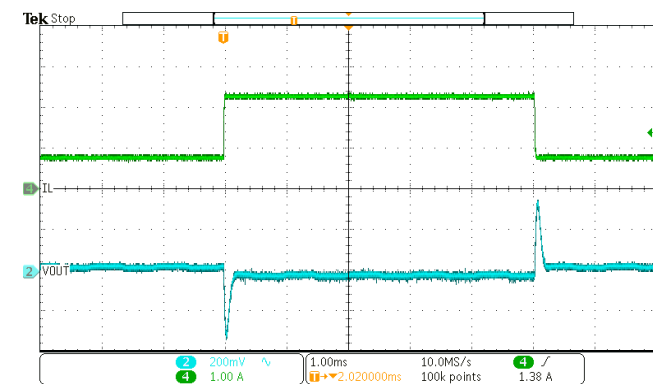
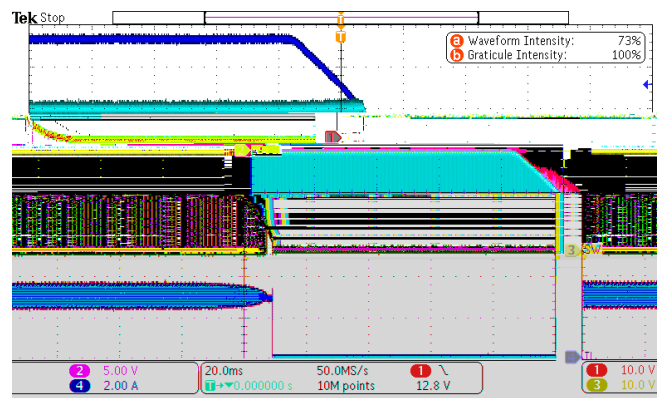
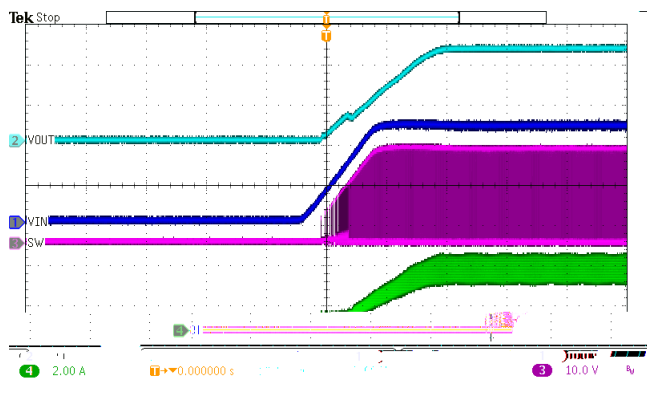
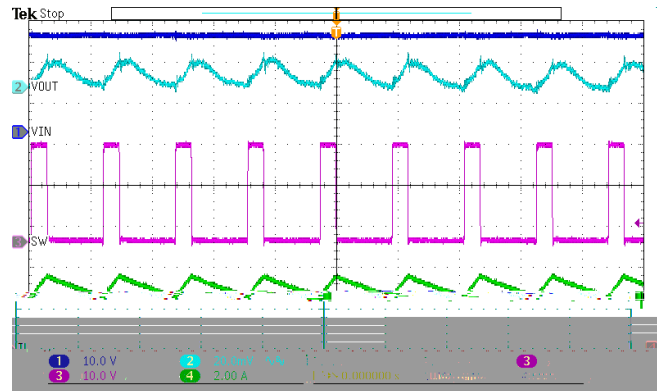
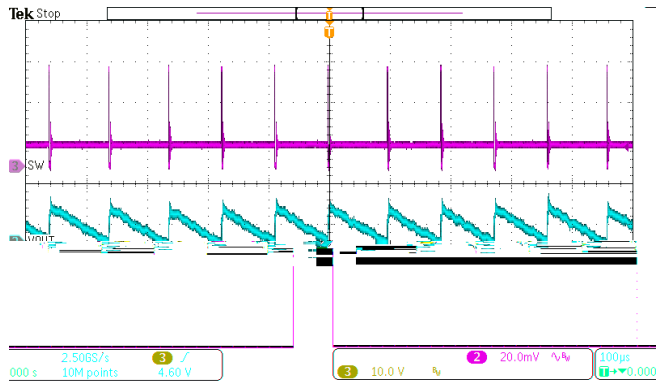
Inductor Selection

(4)

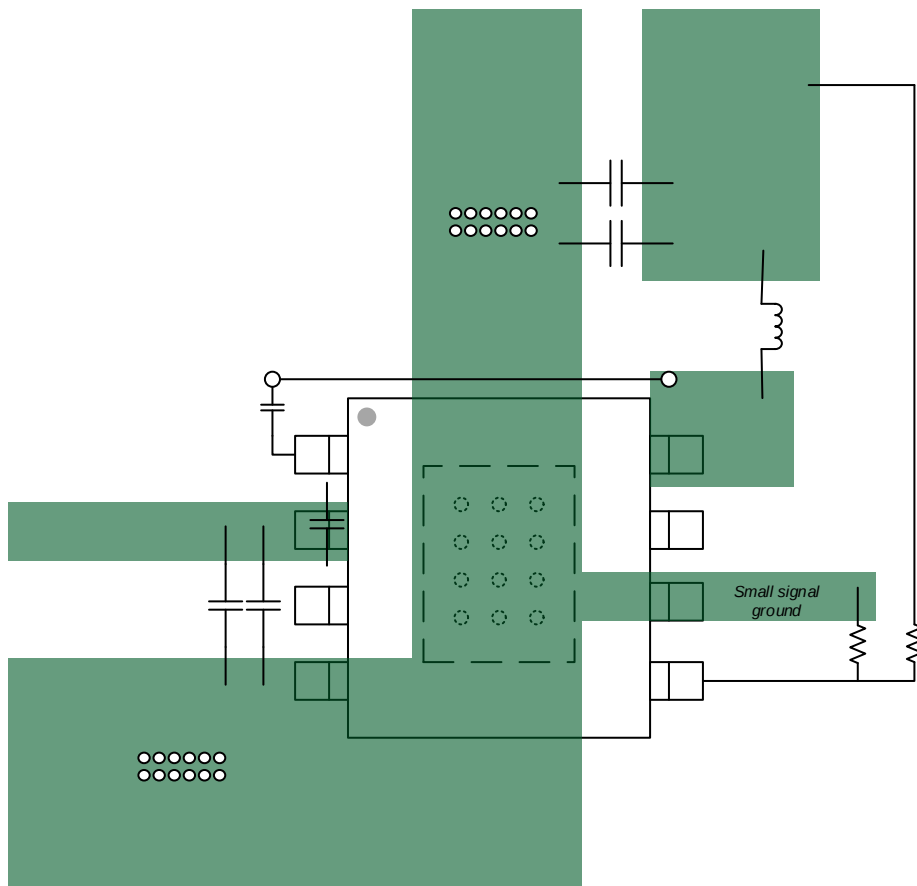
-

(5)

Application Waveforms

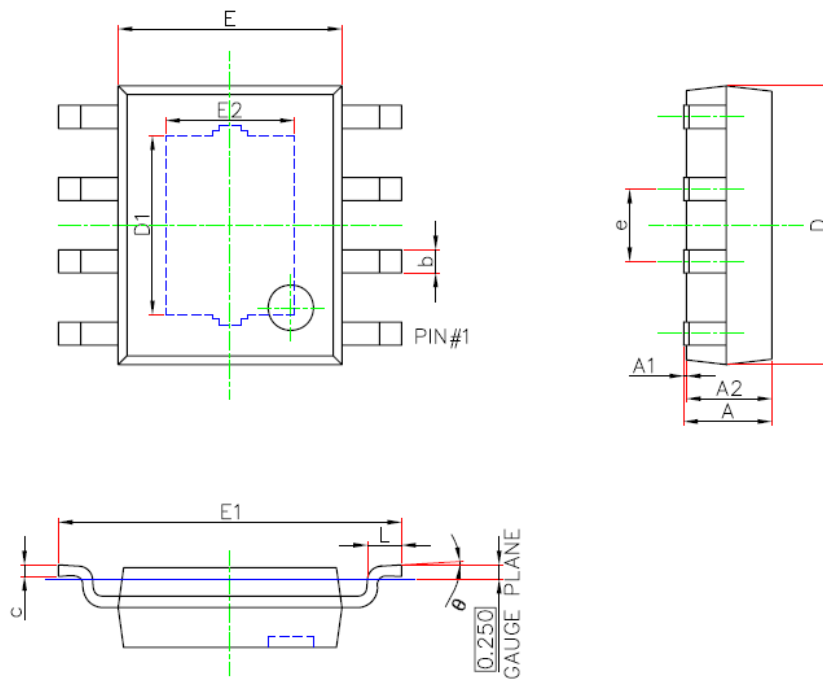


Layout Guideline



Thermal Considerations

•



θ				

NOTE:

- 1.
- 2.
- 3.
- 4.
- 5.
- 6.

